

# 74HC7541; 74HCT7541

Octal Schmitt trigger buffer/line driver; 3-state

Rev. 6 — 16 December 2013

Product data sheet

## 1. General description

The 74HC7541; 74HCT7541 is an 8-bit buffer/line driver with Schmitt-trigger inputs and 3-state outputs. The device features two output enables ( $\overline{OE}1$  and  $\overline{OE}2$ ). A HIGH on  $\overline{OE}n$  causes the outputs to assume a high-impedance OFF-state. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of  $V_{CC}$ . Schmitt trigger inputs transform slowly changing input signals into sharply defined jitter-free output signals.

## 2. Features and benefits

- Non-inverting outputs
- Low-power dissipation
- Input levels:
  - ◆ For 74HC7541: CMOS level
  - ◆ For 74HCT7541: TTL level
- Complies with JEDEC standard no. 7A
- ESD protection:
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V
- Multiple package options
- Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$

## 3. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
74HC7541N 74HCT7541N	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	DIP20	plastic dual in-line package; 20 leads (300 mil)	SOT146-1
74HC7541D 74HCT7541D	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SO20	plastic small outline package; 20 leads; body width 7.5 mm	SOT163-1
74HC7541DB	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SSOP20	plastic shrink small outline package; 20 leads; body width 5.3 mm	SOT339-1
74HC7541PW 74HCT7541PW	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	TSSOP20	plastic thin shrink small outline package; 20 leads; body width 4.4 mm	SOT360-1



## 4. Functional diagram

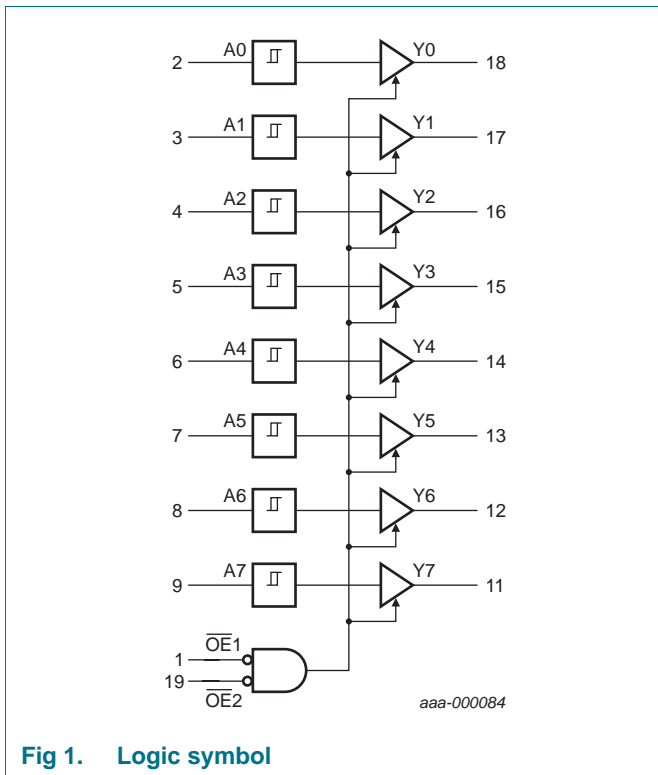


Fig 1. Logic symbol

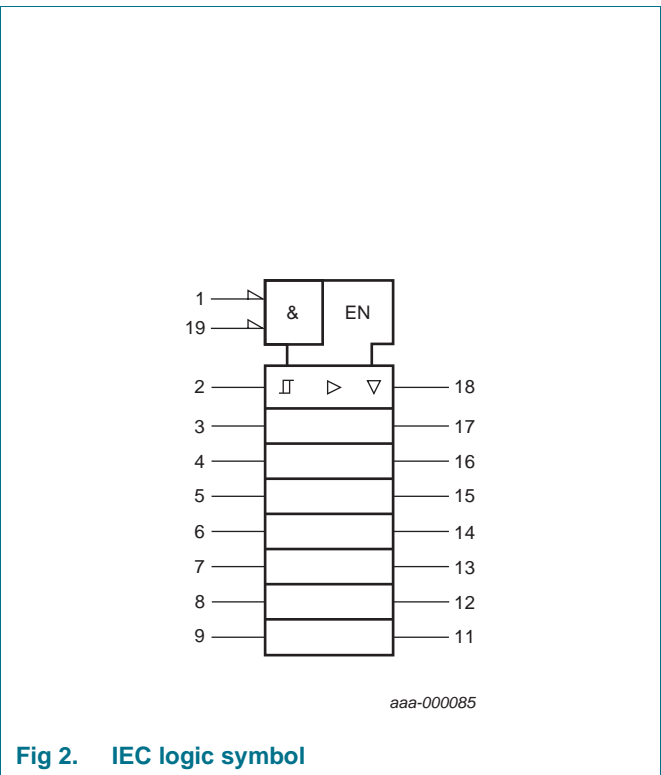


Fig 2. IEC logic symbol

## 5. Pinning information

### 5.1 Pinning

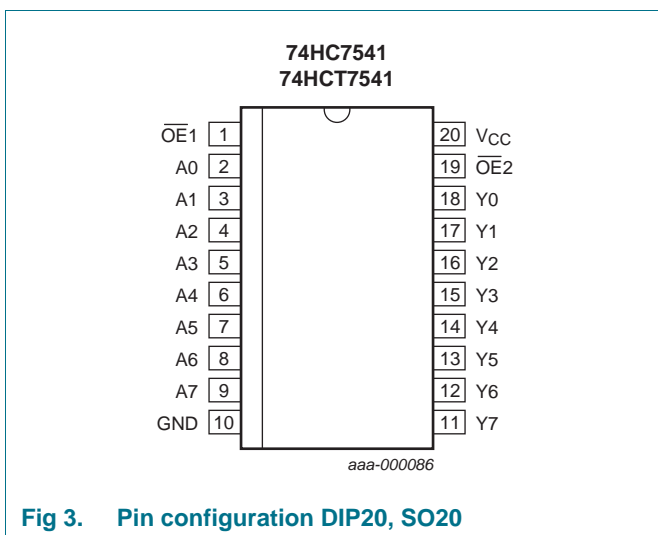


Fig 3. Pin configuration DIP20, SO20

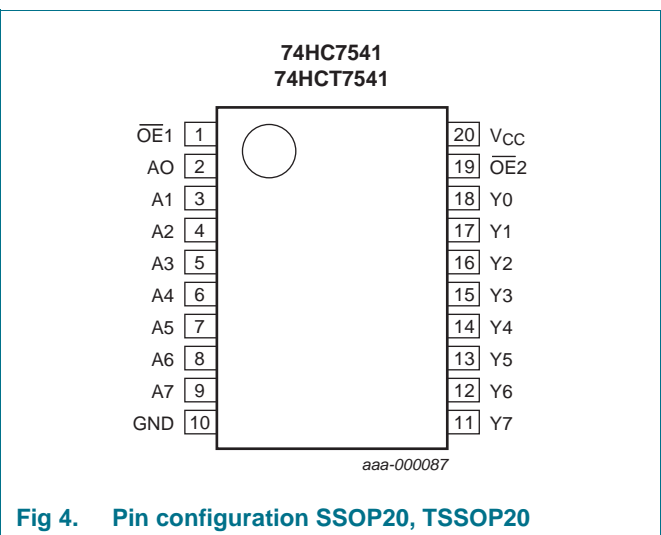


Fig 4. Pin configuration SSOP20, TSSOP20

## 5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
$\overline{OE}1$	1	output enable input (active LOW)
A0 to A7	2, 3, 4, 5, 6, 7, 8, 9	data input
GND	10	ground (0 V)
Y0 to Y7	18, 17, 16, 15, 14, 13, 12, 11	data output
$\overline{OE}2$	19	output enable input (active LOW)
V <sub>CC</sub>	20	supply voltage

## 6. Functional description

Table 3. Functional table<sup>[1]</sup>

Control		Input	Output
$\overline{OE}1$	$\overline{OE}2$	A <sub>n</sub>	Y <sub>n</sub>
L	L	L	L
L	L	H	H
X	H	X	Z
H	X	X	Z

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

## 7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		-0.5	+7	V
I <sub>IK</sub>	input clamping current	V <sub>I</sub> < -0.5 V or V <sub>I</sub> > V <sub>CC</sub> + 0.5 V	<sup>[1]</sup> -	±20	mA
I <sub>OK</sub>	output clamping current	V <sub>O</sub> < -0.5 V or V <sub>O</sub> > V <sub>CC</sub> + 0.5 V	<sup>[1]</sup> -	±20	mA
I <sub>O</sub>	output current	-0.5 V < V <sub>O</sub> < V <sub>CC</sub> + 0.5 V	-	±35	mA
I <sub>CC</sub>	supply current		-	70	mA
I <sub>GND</sub>	ground current		-70	-	mA
T <sub>stg</sub>	storage temperature		-65	+150	°C
P <sub>tot</sub>	total power dissipation		<sup>[2]</sup>		
	DIP20		-	750	mW
	SO20, SSOP20, TSSOP20		-	500	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For DIP20 packages: above 70 °C the value of P<sub>tot</sub> derates linearly with 12 mW/K.  
 For SO20 packages: above 70 °C the value of P<sub>tot</sub> derates linearly with 8 mW/K.  
 For SSOP20 and TSSOP20 packages: above 60 °C the value of P<sub>tot</sub> derates linearly with 5.5 mW/K.

## 8. Recommended operating conditions

**Table 5. Recommended operating conditions**

Voltages are referenced to GND (ground = 0 V)

Symbol	Parameter	Conditions	74HC7541			74HCT7541			Unit
			Min	Typ	Max	Min	Typ	Max	
V <sub>CC</sub>	supply voltage		2.0	5.0	6.0	4.5	5.0	5.5	V
V <sub>I</sub>	input voltage		0	-	V <sub>CC</sub>	0	-	V <sub>CC</sub>	V
V <sub>O</sub>	output voltage		0	-	V <sub>CC</sub>	0	-	V <sub>CC</sub>	V
T <sub>amb</sub>	ambient temperature		-40	+25	+125	-40	+25	+125	°C

## 9. Static characteristics

**Table 6. Static characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	T <sub>amb</sub> = 25 °C			T <sub>amb</sub> = -40 °C to +85 °C		T <sub>amb</sub> = -40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	

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V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>T+</sub> or V <sub>T-</sub>								
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 6.0 V	5.9	6.0	-	5.9	-	5.9	-	V
		I <sub>O</sub> = -6.0 mA; V <sub>CC</sub> = 4.5 V	3.98	4.32	-	3.84	-	3.7	-	V
		I <sub>O</sub> = -7.8 mA; V <sub>CC</sub> = 6.0 V	5.48	5.81	-	5.34	-	5.2	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>T+</sub> or V <sub>T-</sub>								
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 6.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 6.0 mA; V <sub>CC</sub> = 4.5 V	-	0.15	0.26	-	0.33	-	0.4	V
		I <sub>O</sub> = 7.8 mA; V <sub>CC</sub> = 6.0 V	-	0.16	0.26	-	0.33	-	0.4	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 6.0 V	-	-	±0.1	-	±1.0	-	±1.0	μA
I <sub>OZ</sub>	OFF-state output current	per input pin; V <sub>I</sub> = V <sub>T+</sub> or V <sub>T-</sub> ; V <sub>O</sub> = V <sub>CC</sub> or GND; other inputs at V <sub>CC</sub> or GND; V <sub>CC</sub> = 6.0 V; I <sub>O</sub> = 0 A	-	-	±0.5	-	±5.0	-	±10	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 6.0 V	-	-	8.0	-	80	-	160	μA
C <sub>I</sub>	input capacitance		-	3.5	-	-	-	-	-	pF

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V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>T+</sub> or V <sub>T-</sub> ; V <sub>CC</sub> = 4.5 V								
		I <sub>O</sub> = -20 μA	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -6.0 mA	3.98	4.32	-	3.84	-	3.7	-	V

**Table 6. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	T <sub>amb</sub> = 25 °C			T <sub>amb</sub> = -40 °C to +85 °C		T <sub>amb</sub> = -40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>T+</sub> or V <sub>T-</sub> ; V <sub>CC</sub> = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA;	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 6.0 mA;	-	0.15	0.26	-	0.33	-	0.4	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 5.5 V	-	-	±0.1	-	±1.0	-	±1.0	μA
I <sub>OZ</sub>	OFF-state output current	per input pin; V <sub>I</sub> = V <sub>T+</sub> or V <sub>T-</sub> ; V <sub>O</sub> = V <sub>CC</sub> or GND; other inputs at V <sub>CC</sub> or GND; V <sub>CC</sub> = 5.5 V; I <sub>O</sub> = 0 A	-	-	±0.5	-	±5.0	-	±10	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 5.5 V	-	-	8.0	-	80	-	160	μA
ΔI <sub>CC</sub>	additional supply current	per input pin; I <sub>O</sub> = 0 A; V <sub>I</sub> = V <sub>CC</sub> - 2.1 V; other inputs at V <sub>CC</sub> or GND; V <sub>CC</sub> = 4.5 V to 5.5 V	-	-	-	-	-	-	-	-
		An input	-	20	72	-	90	-	98	μA
		$\overline{\text{OEn}}$ input	-	130	468	-	585	-	637	μA
C <sub>I</sub>	input capacitance		-	3.5	-	-	-	-	-	pF

## 10. Dynamic characteristics

**Table 7. Dynamic characteristics**GND = 0 V; C<sub>L</sub> = 50 pF; for test circuit see [Figure 7](#).

Symbol	Parameter	Conditions	T <sub>amb</sub> = 25 °C			T <sub>amb</sub> = -40 °C to +125 °C		Unit
			Min	Typ	Max	Max (85 °C)	Max (125 °C)	
<b>74HC7541</b>								
t <sub>pd</sub>	propagation delay	An to Yn; see <a href="#">Figure 5</a>						
		V <sub>CC</sub> = 2.0 V	-	39	120	150	180	ns
		V <sub>CC</sub> = 4.5 V	-	14	24	30	36	ns
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF	-	10	-	-	-	ns
		V <sub>CC</sub> = 6.0 V	-	11	20	26	32	ns
t <sub>en</sub>	enable time	$\overline{\text{OEn}}$ to Yn; see <a href="#">Figure 6</a>						
		V <sub>CC</sub> = 2.0 V	-	44	160	200	240	ns
		V <sub>CC</sub> = 4.5 V	-	16	32	40	48	ns
		V <sub>CC</sub> = 6.0 V	-	13	27	34	41	ns
t <sub>dis</sub>	disable time	$\overline{\text{OEn}}$ to Yn; see <a href="#">Figure 6</a>						
		V <sub>CC</sub> = 2.0 V	-	58	160	200	240	ns
		V <sub>CC</sub> = 4.5 V	-	21	32	40	48	ns
		V <sub>CC</sub> = 6.0 V	-	17	27	34	41	ns

**Table 7. Dynamic characteristics**  
*GND = 0 V; C<sub>L</sub> = 50 pF; for test circuit see [Figure 7](#).*

Symbol	Parameter	Conditions	T <sub>amb</sub> = 25 °C			T <sub>amb</sub> = -40 °C to +125 °C		Unit	
			Min	Typ	Max	Max (85 °C)	Max (125 °C)		
t <sub>t</sub>	transition time	see <a href="#">Figure 5</a>	<a href="#">[2]</a>						
		V <sub>CC</sub> = 2.0 V	-	14	60	75	90	ns	
		V <sub>CC</sub> = 4.5 V	-	5	12	15	18	ns	
		V <sub>CC</sub> = 6.0 V	-	4	10	13	15	ns	
C <sub>PD</sub>	power dissipation capacitance	per package; V <sub>I</sub> = GND to V <sub>CC</sub>	<a href="#">[3]</a>	-	30	-	-	-	pF

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t <sub>pd</sub>	propagation delay	An to Y <sub>n</sub> ; see <a href="#">Figure 5</a>	<a href="#">[1]</a>						
		V <sub>CC</sub> = 4.5 V	-	19	32	40	48	ns	
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF	-	16	-	-	-	ns	
t <sub>en</sub>	enable time	$\overline{\text{OEn}}$ to Y <sub>n</sub> ; see <a href="#">Figure 6</a>	<a href="#">[1]</a>						
		V <sub>CC</sub> = 4.5 V	-	18	32	40	48	ns	
t <sub>dis</sub>	disable time	$\overline{\text{OEn}}$ to Y <sub>n</sub> ; see <a href="#">Figure 6</a>	<a href="#">[1]</a>						
		V <sub>CC</sub> = 4.5 V	-	20	32	40	48	ns	
t <sub>t</sub>	transition time	V <sub>CC</sub> = 4.5 V; see <a href="#">Figure 5</a>	<a href="#">[2]</a>	-	5	12	15	18	ns
C <sub>PD</sub>	power dissipation capacitance	per package; V <sub>I</sub> = GND to V <sub>CC</sub> - 1.5 V	<a href="#">[3]</a>	-	32	-	-	-	pF

- [1] t<sub>pd</sub> is the same as t<sub>PLH</sub> and t<sub>PHL</sub>.  
 t<sub>en</sub> is the same as t<sub>PZL</sub> and t<sub>PZH</sub>.  
 t<sub>dis</sub> is the same as t<sub>PLZ</sub> and t<sub>PHZ</sub>.

- [2] t<sub>t</sub> is the same as t<sub>THL</sub> and t<sub>TLH</sub>.

- [3] C<sub>PD</sub> is used to determine the dynamic power dissipation (P<sub>D</sub> in μW):

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum (C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f<sub>i</sub> = input frequency in MHz;

f<sub>o</sub> = output frequency in MHz;

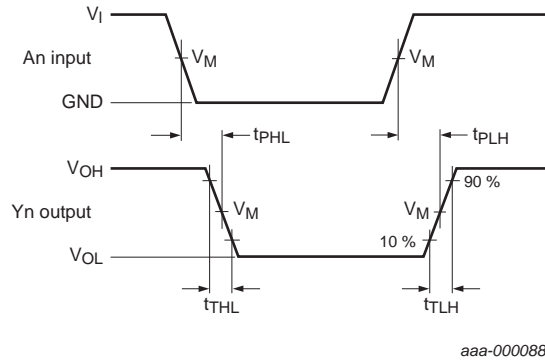
C<sub>L</sub> = output load capacitance in pF;

V<sub>CC</sub> = supply voltage in V;

N = number of inputs switching;

$\sum (C_L \times V_{CC}^2 \times f_o)$  = sum of outputs.

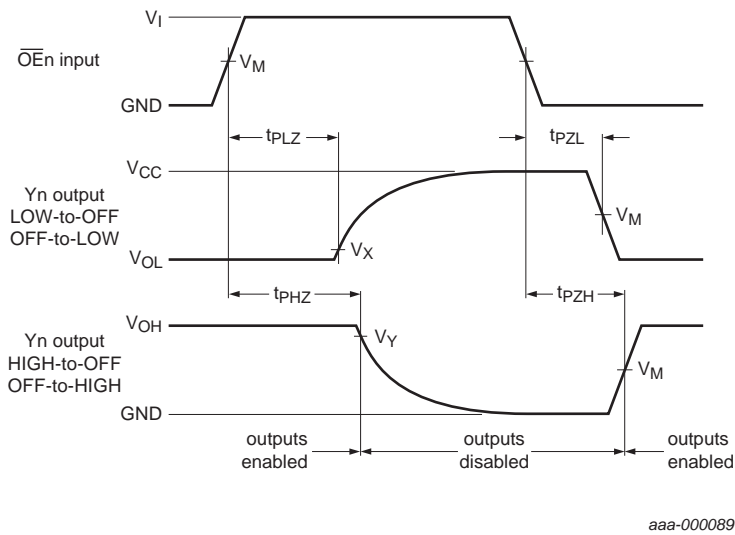
11. Waveforms



Measurement points are given in [Table 8](#).

$V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

**Fig 5. Input to output propagation delays**



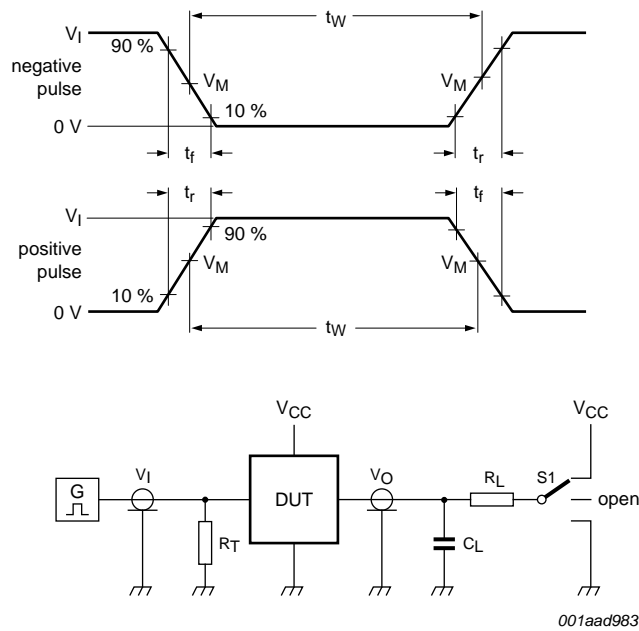
Measurement points are given in [Table 8](#).

$V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

**Fig 6. 3-state enable and disable times**

**Table 8. Measurement points**

Type	Input	Output		
	$V_M$	$V_M$	$V_X$	$V_Y$
74HC7541	$0.5V_{CC}$	$0.5V_{CC}$	$0.1V_{CC}$	$0.9V_{CC}$
74HCT7541	1.3 V	1.3 V	$0.1V_{CC}$	$0.9V_{CC}$



Test data is given in [Table 9](#).

Definitions test circuit:

$R_T$  = Termination resistance should be equal to output impedance  $Z_o$  of the pulse generator

$C_L$  = Load capacitance including jig and probe capacitance

$R_L$  = Load resistance

S1 = Test selection switch

**Fig 7. Test circuit for measuring switching times**

**Table 9. Test data**

Type	Input		Load		S1 position		
	$V_I$	$t_r, t_f$	$C_L$	$R_L$	$t_{PHL}, t_{PLH}$	$t_{PZH}, t_{PHZ}$	$t_{PZL}, t_{PLZ}$
74HC7541	$V_{CC}$	6 ns	15 pF, 50 pF	1 k $\Omega$	open	GND	$V_{CC}$
74HCT7541	3 V	6 ns	15 pF, 50 pF	1 k $\Omega$	open	GND	$V_{CC}$



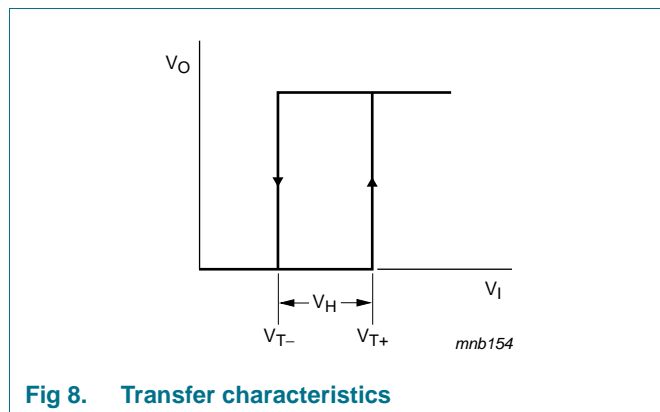
## 12. Transfer characteristics

**Table 10. Transfer characteristics**

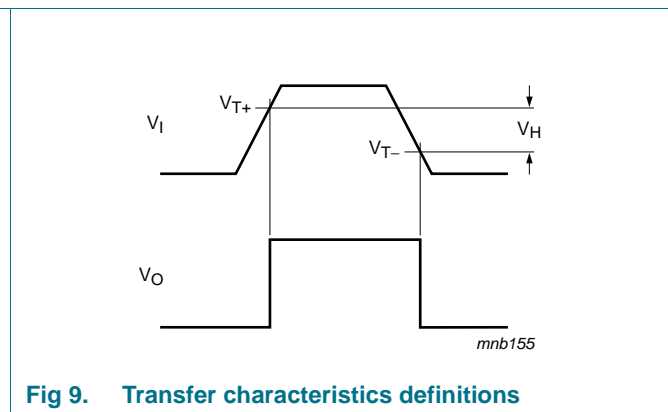
At recommended operating conditions; voltages are referenced to GND (ground = 0 V); see [Figure 8](#) and [Figure 9](#).

Symbol	Parameter	Conditions	T <sub>amb</sub> = 25 °C			T <sub>amb</sub> = -40 °C to +85 °C		T <sub>amb</sub> = -40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
<b>74HC7541</b>										
V <sub>T+</sub>	positive-going threshold voltage	V <sub>CC</sub> = 2.0 V	-	-	1.5	-	1.5	-	1.5	V
		V <sub>CC</sub> = 4.5 V	-	-	3.15	-	3.15	-	3.15	V
		V <sub>CC</sub> = 6.0 V	-	-	4.2	-	4.2	-	4.2	V
V <sub>T-</sub>	negative-going threshold voltage	V <sub>CC</sub> = 2.0 V	0.3	-	-	0.3	-	0.3	-	V
		V <sub>CC</sub> = 4.5 V	1.35	-	-	1.35	-	1.35	-	V
		V <sub>CC</sub> = 6.0 V	1.8	-	-	1.8	-	1.8	-	V
V <sub>H</sub>	hysteresis voltage	V <sub>CC</sub> = 2.0 V	0.1	0.20	-	0.1	-	0.1	-	V
		V <sub>CC</sub> = 4.5 V	0.25	0.40	-	0.25	-	0.25	-	V
		V <sub>CC</sub> = 6.0 V	0.3	0.5	-	0.3	-	0.3	-	V
<b>74HCT7541</b>										
V <sub>T+</sub>	positive-going threshold voltage	V <sub>CC</sub> = 4.5 V	-	-	2.0	-	2.0	-	2.0	V
		V <sub>CC</sub> = 5.5 V	-	-	2.1	-	2.1	-	2.1	V
V <sub>T-</sub>	negative-going threshold voltage	V <sub>CC</sub> = 4.5 V	0.7	-	-	0.64	-	0.6	-	V
		V <sub>CC</sub> = 5.5 V	0.8	-	-	0.74	-	0.7	-	V
V <sub>H</sub>	hysteresis voltage	V <sub>CC</sub> = 4.5 V	0.17	0.23	-	-	-	-	-	V
		V <sub>CC</sub> = 5.5 V	0.17	0.23	-	-	-	-	-	V

## 13. Transfer characteristics waveforms



**Fig 8. Transfer characteristics**



**Fig 9. Transfer characteristics definitions**

14. Package outline

DIP20: plastic dual in-line package; 20 leads (300 mil)

SOT146-1

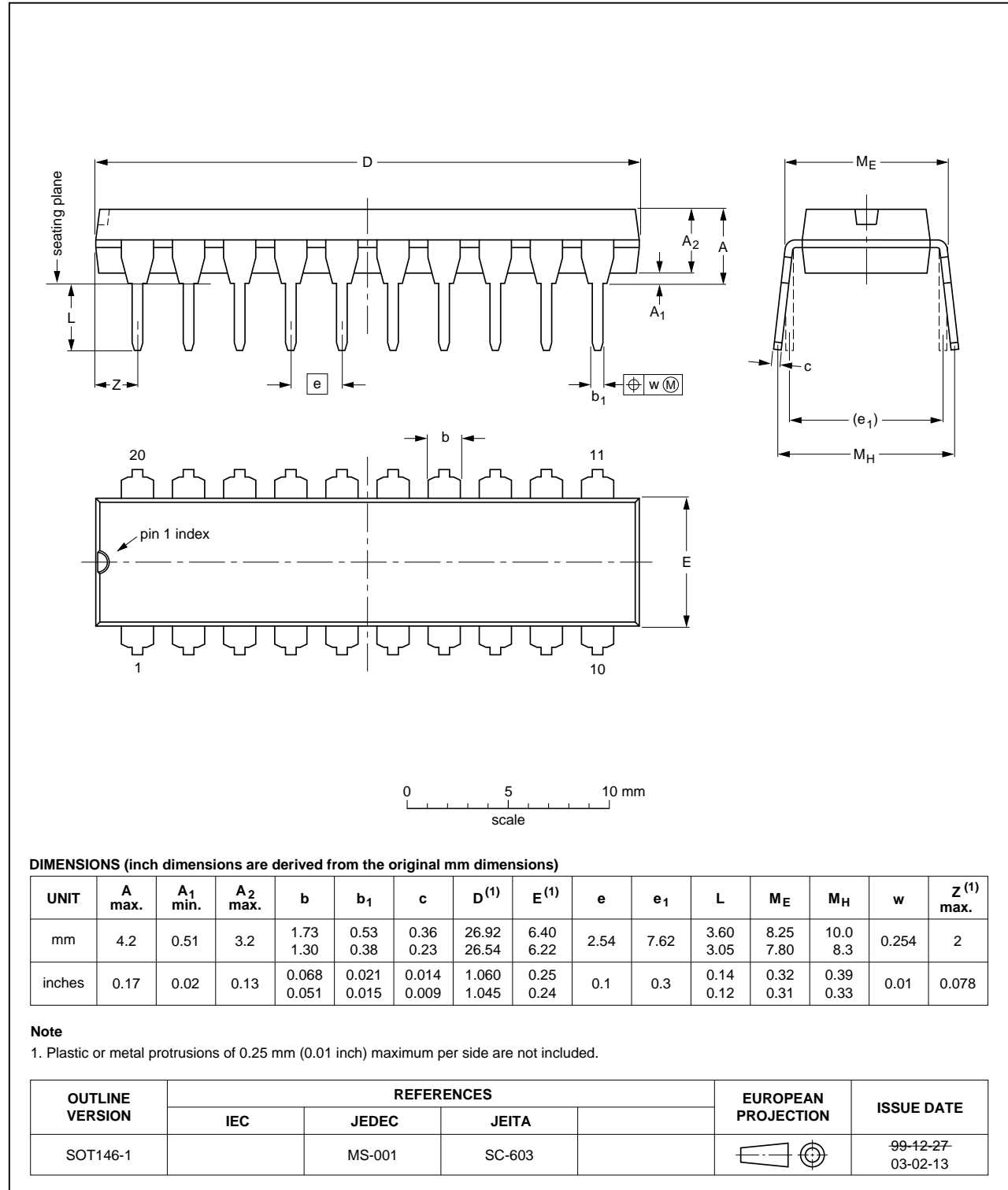


Fig 10. Package outline SOT146-1 (DIP20)

SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1

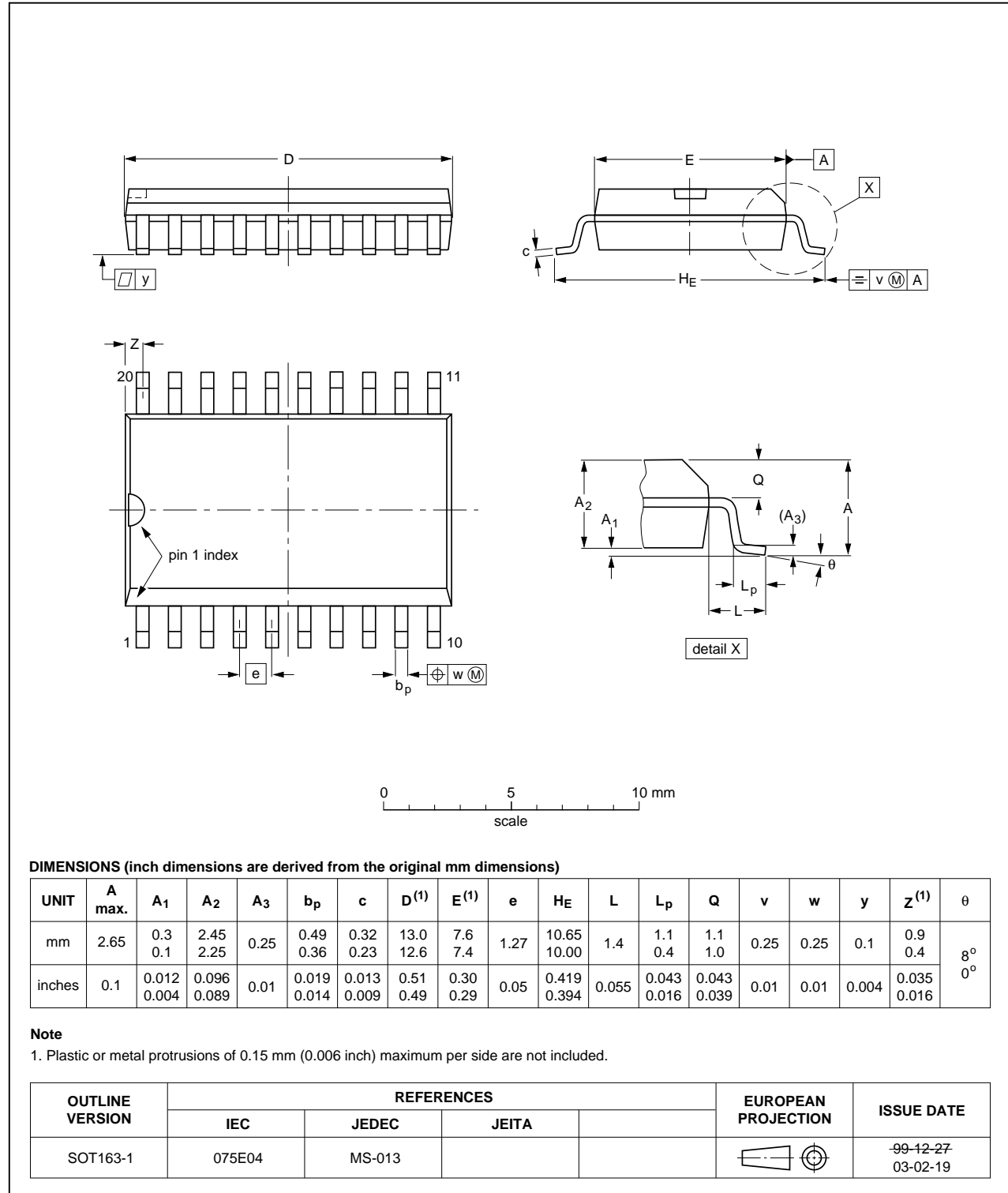


Fig 11. Package outline SOT163-1 (SO20)

SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm

SOT339-1

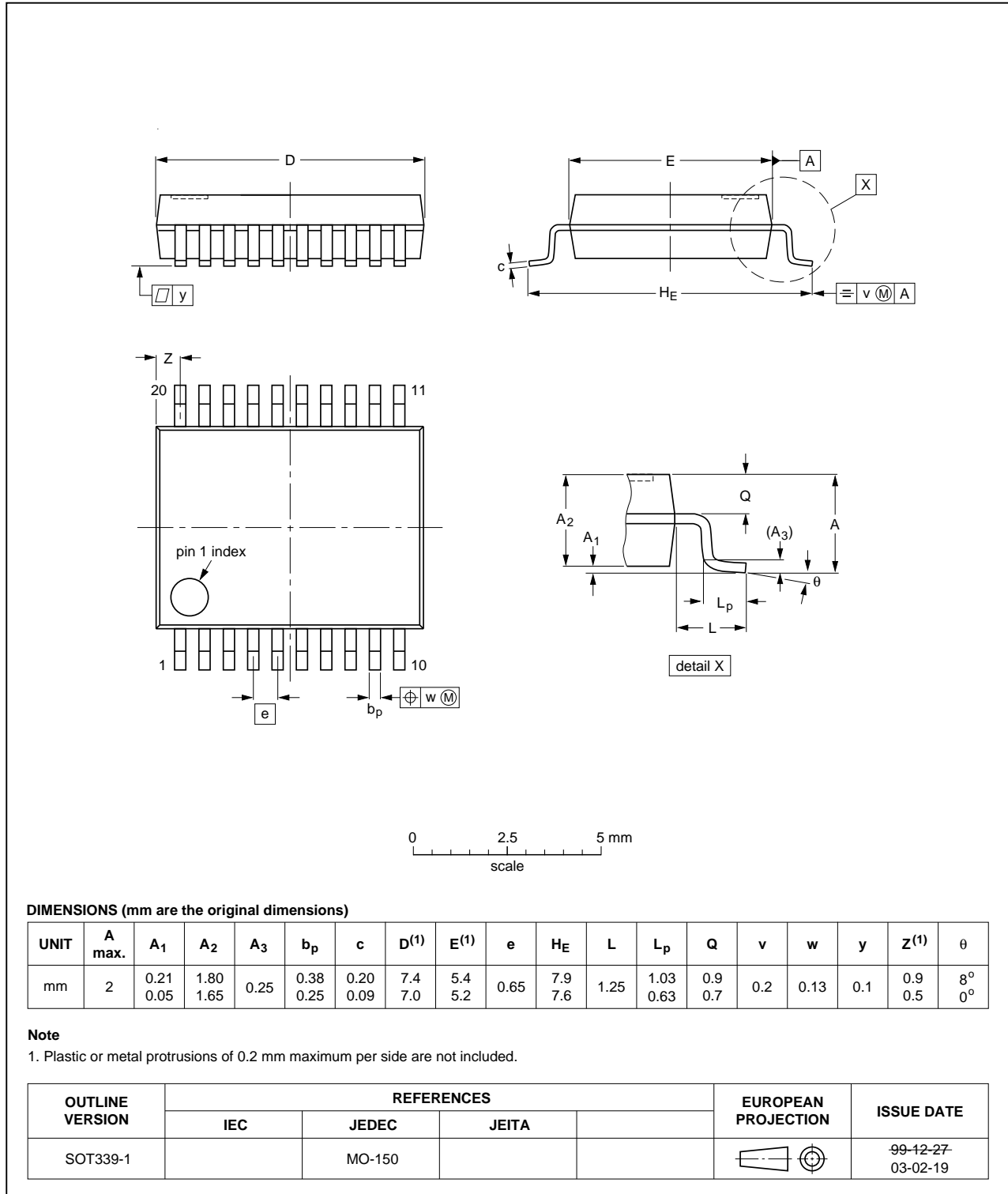


Fig 12. Package outline SOT339-1 (SSOP20)

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1

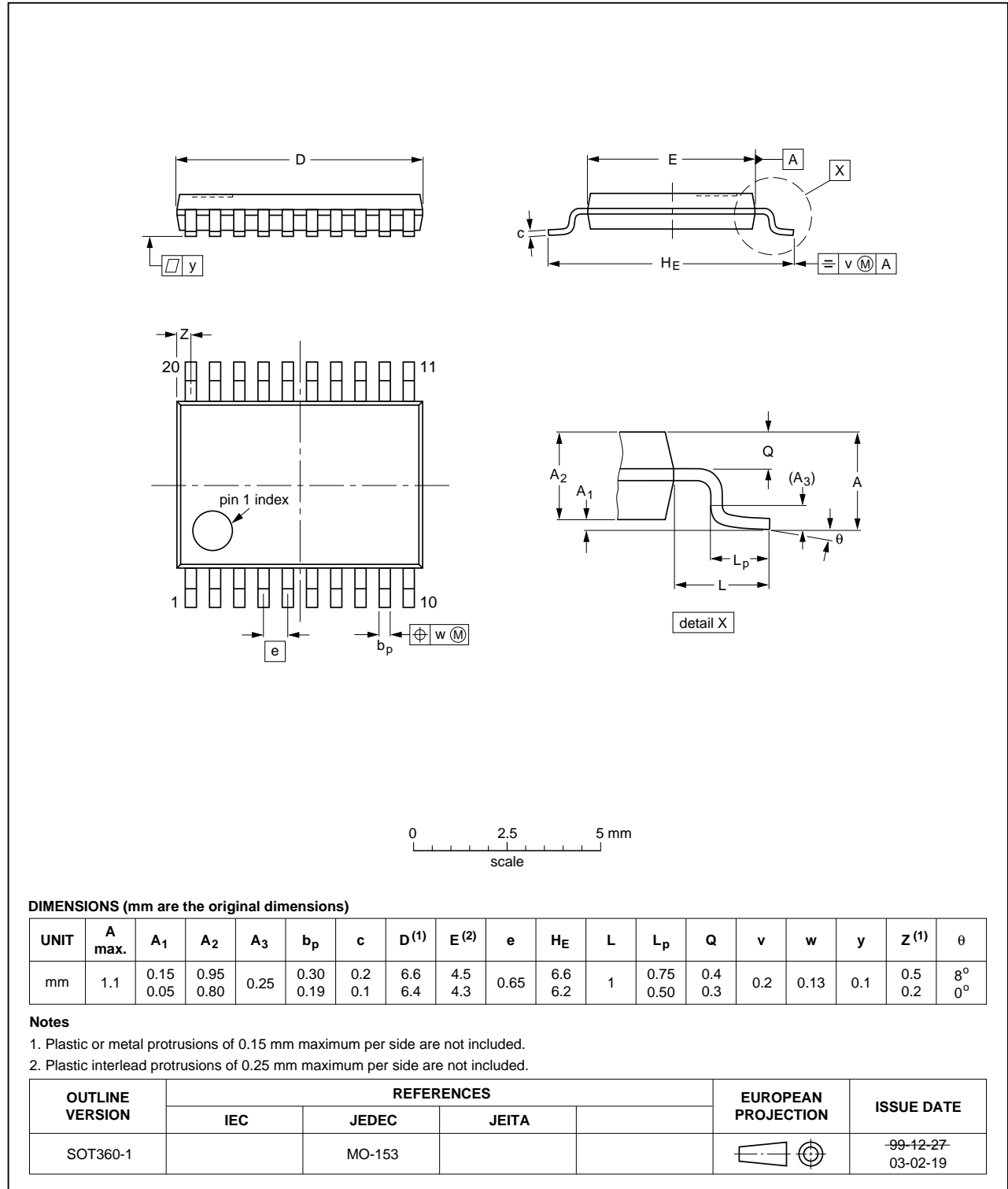


Fig 13. Package outline SOT360-1 (TSSOP20)

## 15. Abbreviations

Table 11. Abbreviations

Acronym	Description
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
LSTTL	Low-power Schottky Transistor-Transistor Logic
MM	Machine Model

## 16. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT7541 v.6	20131216	Product data sheet	-	74HC_HCT7541 v.5
Modifications:	<ul style="list-style-type: none"> <li>New general description (errata).</li> </ul>			
74HC_HCT7541 v.5	20121231	Product data sheet	-	74HC_HCT7541 v.4
Modifications:	<ul style="list-style-type: none"> <li>I<sub>OZ</sub> added to static characteristics table.</li> </ul>			
74HC_HCT7541 v.4	20111219	Product data sheet	-	74HC_HCT7541 v.3
Modifications:	<ul style="list-style-type: none"> <li>Legal pages updated.</li> </ul>			
74HC_HCT7541 v.3	20110725	Product data sheet	-	74HC_HCT7541_CNV v.2
74HC_HCT7541_CNV v.2	19970917	Product specification	-	-

## 17. Legal information

### 17.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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